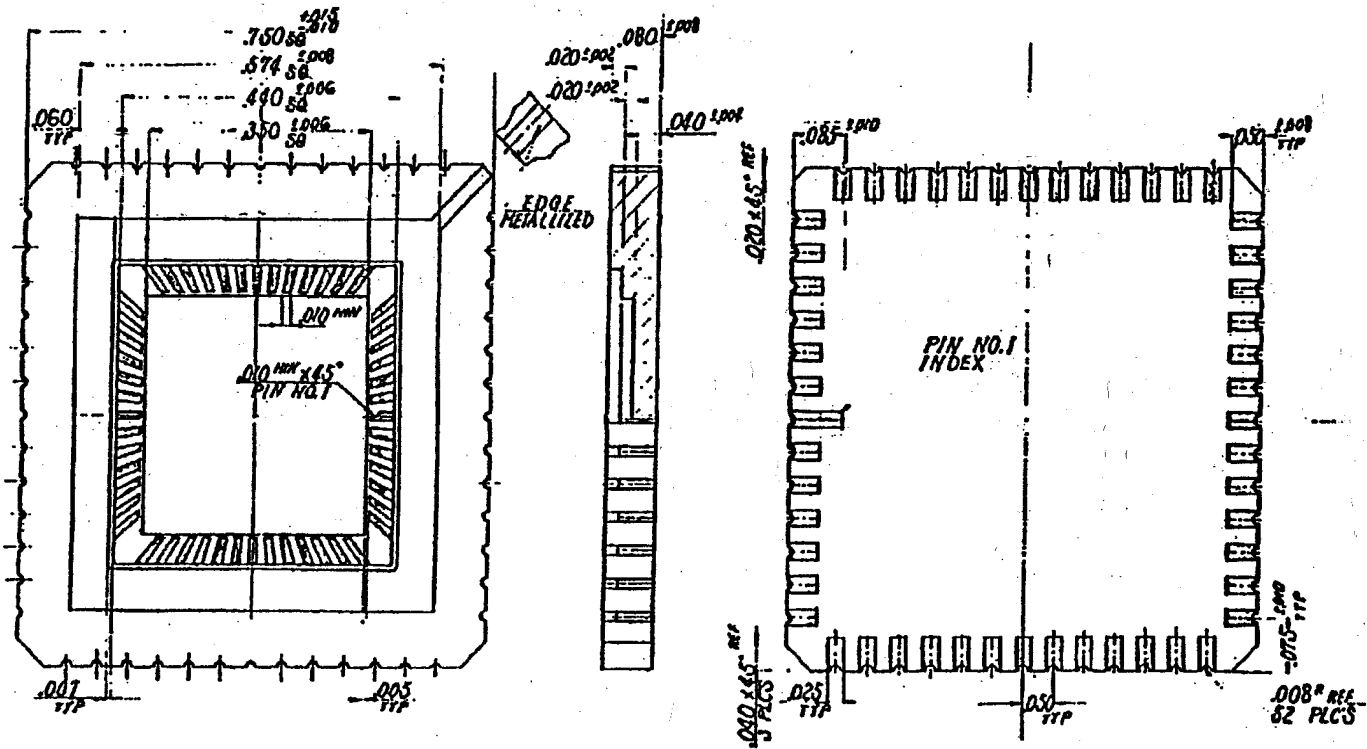


SSM P/N LCC05203



NOTE

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH MIN THICKNESS OVER NICKEL PLATED.
2. SEAL RING FLATNESS .003
3. SEAL RING AND DIE ATTACH PAD ARE NOT GROUND TO A LEAD.

				NAME 52 LEAD CHIP CARRIER		TOLERANCES: UNLESS OTHERWISE SPECIFIED		DRAWN ENR	
				SCALE 8:1		± 1%		CHECKED S	
A ADD: SHEET NO. 2/2				DATE		MATERIAL KYOCERA A-440		APPROVED S	
CHANGE				DATE		MATERIAL KYOTO CERAMIC CO., LTD.		DATE 79-8-16	
						MATERIAL 518TR		DATE PR-92155-A	

